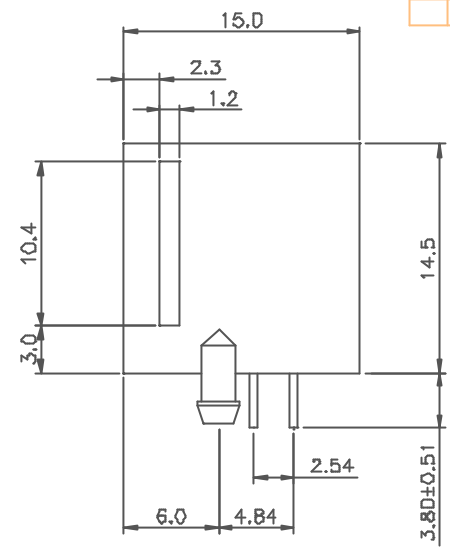
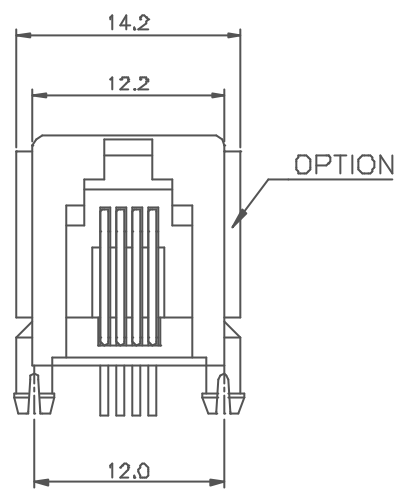


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CH-KD



**NOTES:**

**ELECTRICAL:**

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

**MECHANICAL:**

1. HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE  $\phi 0.46\text{mm}$ .
3. PLATING : GOLD PLATING OVER NICKEL.
4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

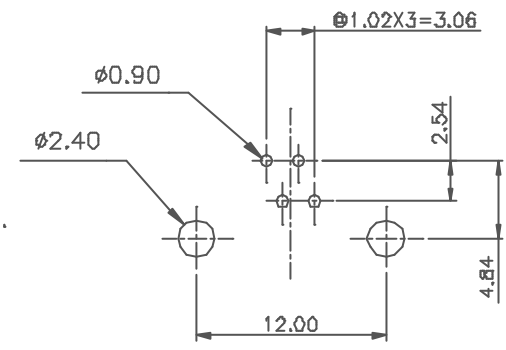
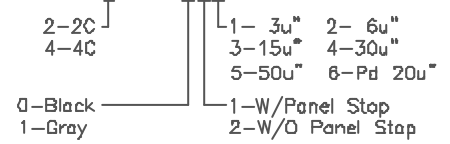
**ENVIRONMENTAL:**

1. STORAGE :  $-40^{\circ}\text{C}$  TO  $+85^{\circ}\text{C}$ .
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$ .

MATES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.

PART NUMBER: E554X-HOLXXX



**PC Board Layout**

DETAIL LIST	DIM (INCH)	DFTO: <b>YNC</b> DATE: <b>7/28/98</b> CHKD: <b>JACKKEY</b> DATE: <b>7/31/98</b> WFO: <b>LWJ</b> DATE: <b>7/31/98</b> APPVL: <b>LWJ</b> DATE: <b>7/31/98</b>	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED NM .0 ± 0.2 ± .00 ± 0.15 ± .000 ± 0.075 ±	MATERIAL :  QTY :  FINISH :  SCALE : <b>3 : 1</b>	TITLE: <b>SIDE ENTRY L/P PCB JACK (外六内四)</b>	
	ANGLES ± 0.5  THIRD ANGLE PROJECTION	DRAWING NO. <b>GE553A08</b> SIZE <b>A3</b> /PART NO. <b>SEE NOTE</b> REV <b>7/98/00</b> DID NOT SCALE DRAWING    SHEET <b>0F</b>	SHEET <b>0F</b>	
	8   7   6   5   4   3   2   1		A   B   C   D   E   F   G   H	